

Voltage Detector (Reset) IC Series

Over Voltage Detector IC

BD71L3SHFV

General Description

ROHM's Over Voltage Detector ICs are highly accurate, with ultra-low current consumption feature that uses CMOS process. The lineup includes N-channel open drain output with detection voltage of 3.83 V and hysteresis voltage of 30mV. It is most suitable for monitoring the charge of a lithium-ion battery.

Features

- High Accuracy Detection Voltage
- Ultra-low Current Consumption
- Nch Open Drain Output
- Wide Operating Temperature Range
- Very Small, Lightweight and Thin Package

Key Specifications

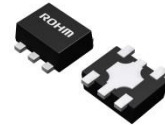
- Detection Voltage: 3.83 V (Typ)
- Ultra-Low Current Consumption: 0.7 μ A (Typ)
- Operation Temperature Range: -40 °C to +125 °C

Package

HVSOF5:

W(Typ) x D(Typ) x H(Max)

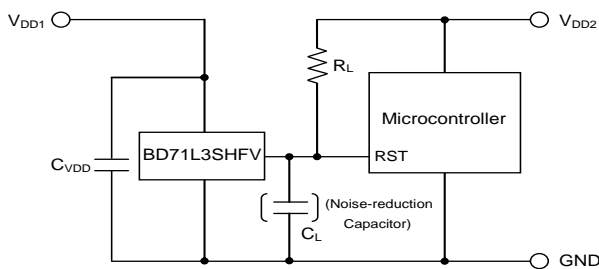
1.60 mm x 1.60 mm x 0.60 mm



Application

All electronics devices that requires over voltage detection

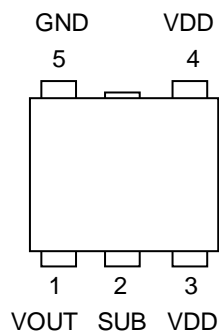
Typical Application Circuit



Pin Configuration

HVSOF5

TOP VIEW



Pin Description

HVSOF5		
PIN No.	PIN NAME	Function
1	VOUT	Output pin
2	SUB	Substrate
3	VDD	Power supply voltage
4	VDD	Power supply voltage
5	GND	GND

The SUB pin connect to VDD pin.

Block Diagram

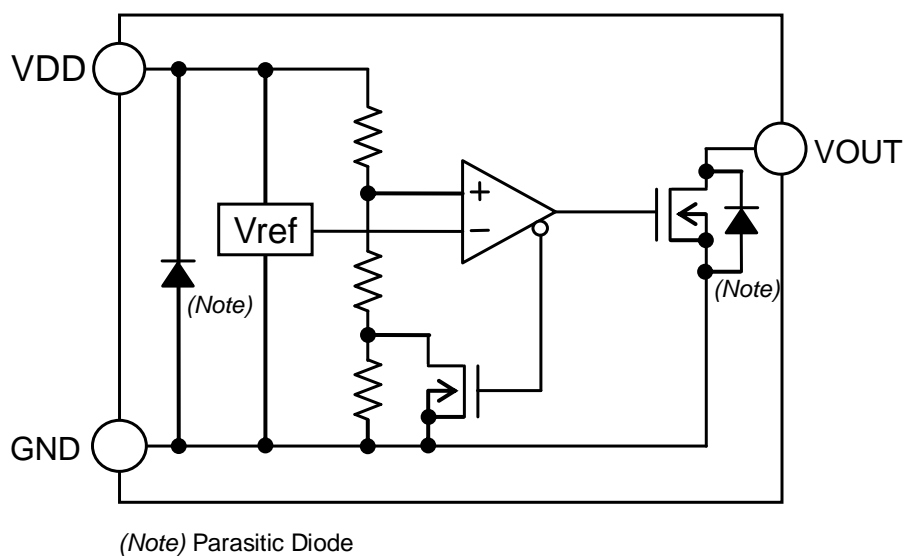


Figure 1. BD71L3SHFV Block Diagram

Absolute Maximum Ratings (Ta=25 °C)

Parameter	Symbol	Limit	Unit
Power Supply Voltage	V _{DD} - GND	-0.3 to +7	V
Output Voltage	Nch Open Drain Output V _{OUT}	GND-0.3 to +7	V
Output Current	I _O	70	mA
Maximum Junction Temperature	T _{jmax}	+150	°C
Storage Temperature Range	T _{stg}	-55 to +150	°C

Caution 1: Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

Caution 2: Should by any chance the maximum junction temperature rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. In case of exceeding this absolute maximum rating, design a PCB with thermal resistance taken into consideration by increasing board size and copper area so as not to exceed the maximum junction temperature rating.

Thermal Resistance (Note 1)

Parameter	Symbol	Thermal Resistance (Typ)		Unit
		1s ^(Note 3)	2s2p ^(Note 4)	
HVSOF5				
Junction to Ambient	θ _{JA}	358.2	85.3	°C/W
Junction to Top Characterization Parameter ^(Note 2)	Ψ _{JT}	39	21	°C/W

(Note 1) Based on JESD51-2A(Still-Air).

(Note 2) The thermal characterization parameter to report the difference between junction temperature and the temperature at the top center of the outside surface of the component package.

(Note 3) Using a PCB board based on JESD51-3.

(Note 4) Using a PCB board based on JESD51-7.

Layer Number of Measurement Board	Material	Board Size
Single	FR-4	114.3 mm x 76.2 mm x 1.57 mmt

Top	
Copper Pattern	Thickness
Footprints and Traces	70 μm

Layer Number of Measurement Board	Material	Board Size
4 Layers	FR-4	114.3 mm x 76.2 mm x 1.6 mmt

Top		2 Internal Layers		Bottom	
Copper Pattern	Thickness	Copper Pattern	Thickness	Copper Pattern	Thickness
Footprints and Traces	70 μm	74.2 mm x 74.2 mm	35 μm	74.2 mm x 74.2 mm	70 μm

Recommended Operating Condition

Parameter	Symbol	Min	Typ	Max	Unit
Operating Temperature	Topr	-40	+25	+125	°C

Electrical Characteristics (Unless otherwise specified Ta=-40 °C to +125 °C, V_{DD}=1.2 V to 6.0 V)

Parameter	Symbol	Condition	Limit			Unit
			Min	Typ	Max	
Detection Voltage	V _{DET}	R _L =470 kΩ	3.792	3.83	3.868	V
		Ta=25 °C				
		V _{DD} =L→H	3.715	-	3.945	
		Ta=-40 to +125 °C				
Hysteresis Voltage	ΔV _{DET}	V _{DD} =L→H→L, R _L =470 kΩ	-	30	40	mV
Circuit Current when ON	I _{DD1}	V _{DD} =V _{DET} +0.2 V	-	0.60	2.40	μA
Circuit Current when OFF	I _{DD2}	V _{DD} =V _{DET} -0.2 V	-	0.70	2.80	μA
Minimum Operating Voltage	V _{OPL}	V _{OL} ≥0.8 V, R _L =470 kΩ (Note 1)	1.20	-	-	V
“Low” Output Voltage(Nch)	V _{OL}	V _{DD} = V _{DET} +0.2 V, I _{SINK} =4.0 mA	-	-	0.3	V
Output Leak Current	I _{LEAK}	V _{DD} =3.5 V, V _{DS} =6 V	-	-	1.0	μA
Delay Time(H→L)	t _{PHL}	V _{OUT} =V _{DD} →50 % R _L =100 kΩ, C _L =100 pF (Note 1) (Note 2)	-	-	100	μs
Delay Time(L→H)	t _{PLH}	V _{OUT} =GND→50 % R _L =100 kΩ, C _L =100 pF (Note 1) (Note 2)	-	-	100	μs

(Note 1) R_L: Pull-up resistor connected between V_{OUT} and power supply, C_L: Capacitor connected between V_{OUT} and GND.(Note 2) t_{PLH}: V_{DD}=(V_{DET}-0.5 V) → (V_{DET}+0.5 V)t_{PHL}: V_{DD}=(V_{DET}+0.5 V) → (V_{DET}-0.5 V)

Typical Performance Curves

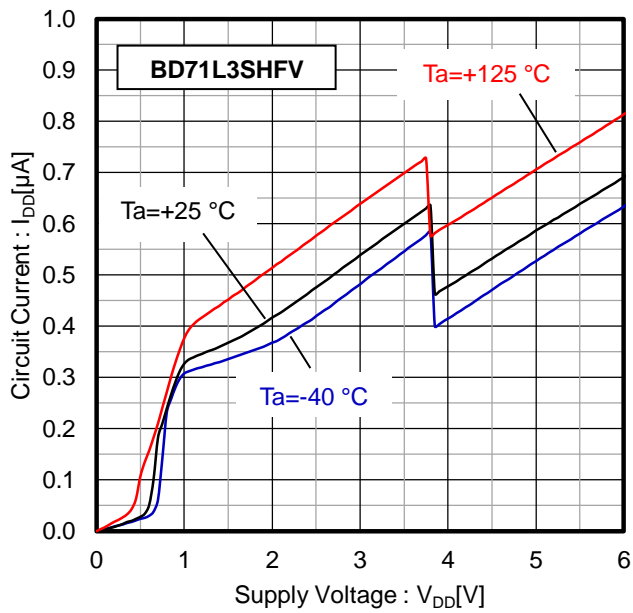


Figure 2. Circuit Current vs Supply Voltage

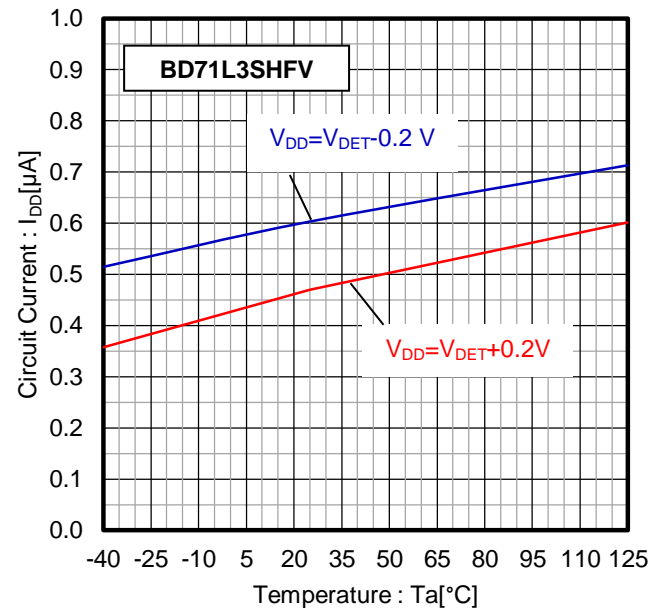


Figure 3. Circuit Current vs Temperature

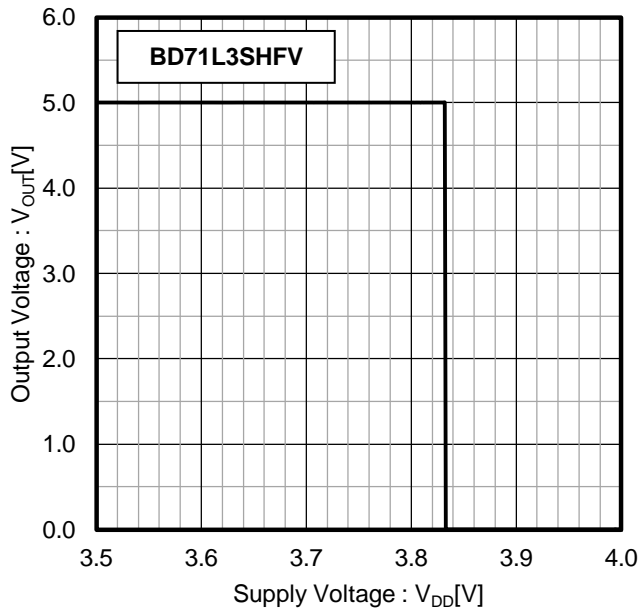


Figure 4. Output Voltage vs Supply Voltage

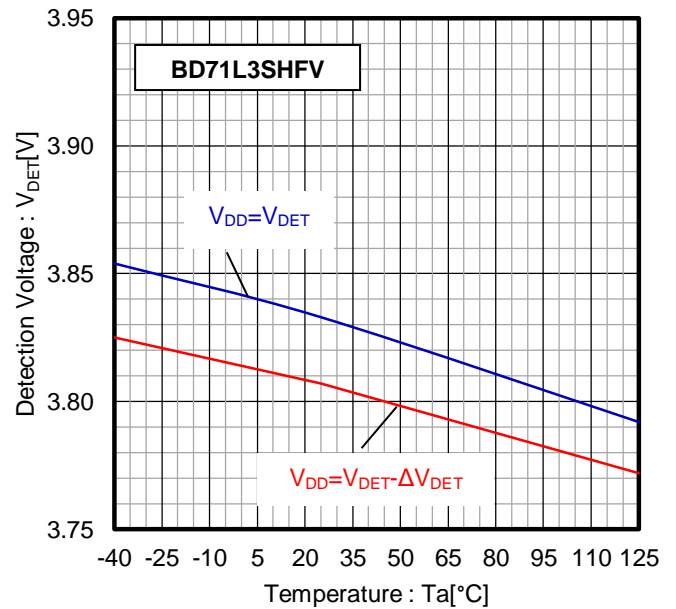


Figure 5. Detection Voltage vs Temperature

Typical Performance Curves - continued

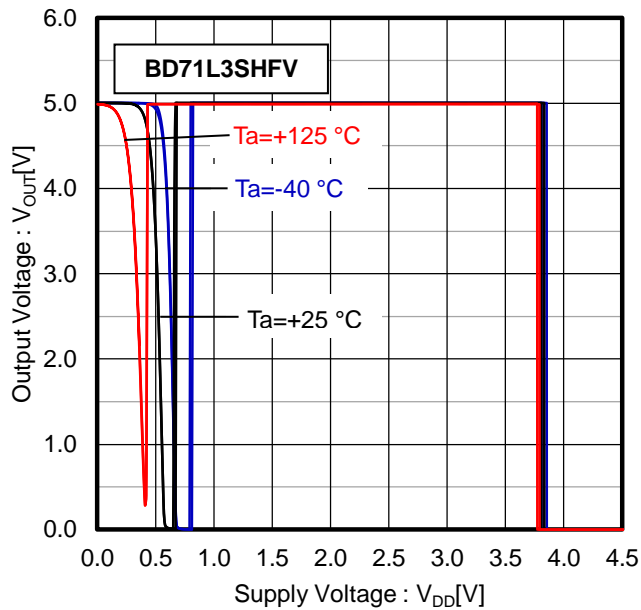


Figure 6. I/O Characteristics
(VOUT Pull-up to 5 V, $R_L=470\text{ k}\Omega$)

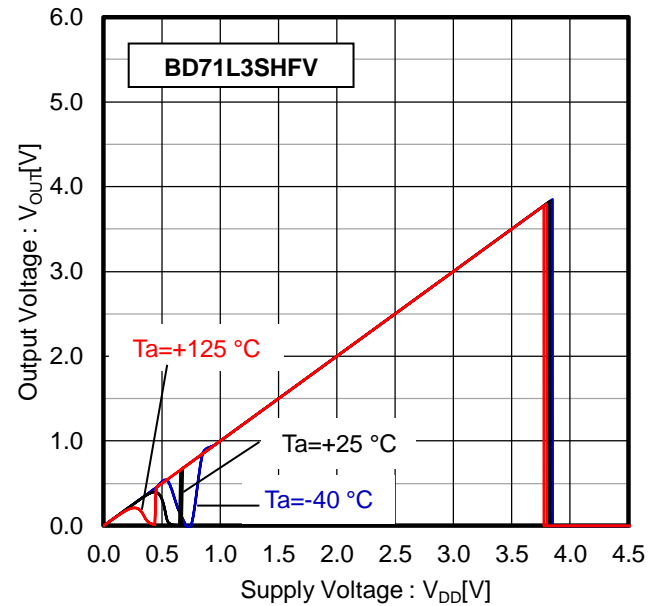


Figure 7. I/O Characteristics
(VOUT Pull-up to V_{DD} , $R_L=470\text{ k}\Omega$)

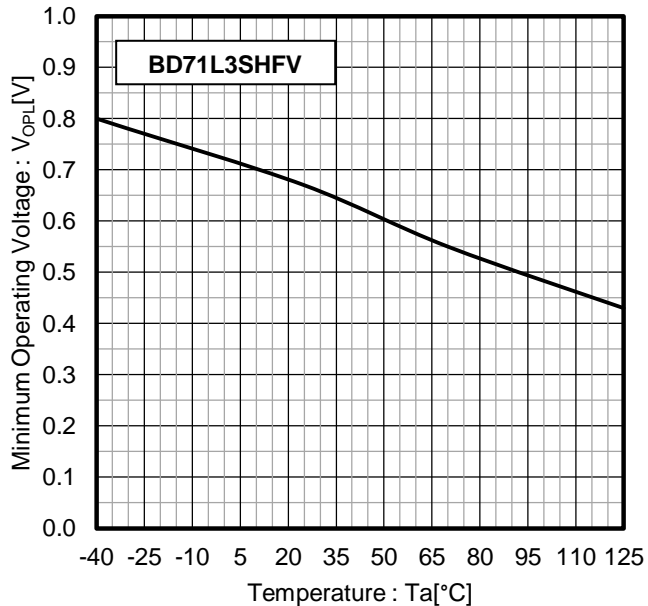


Figure 8. Minimum Operating Voltage vs Temperature
(VOUT Pull-up to 5 V, $R_L=470\text{ k}\Omega$)

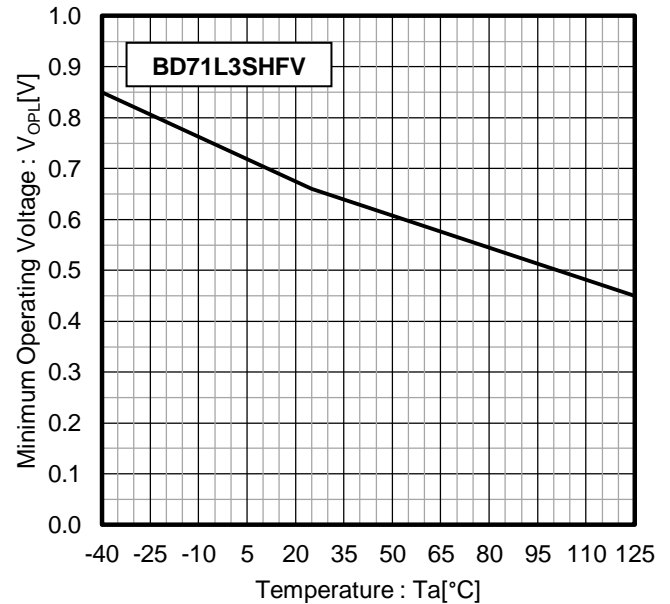


Figure 9. Minimum Operating Voltage vs Temperature
(VOUT Pull-up to V_{DD} , $R_L=470\text{ k}\Omega$)

Typical Performance Curves - continued

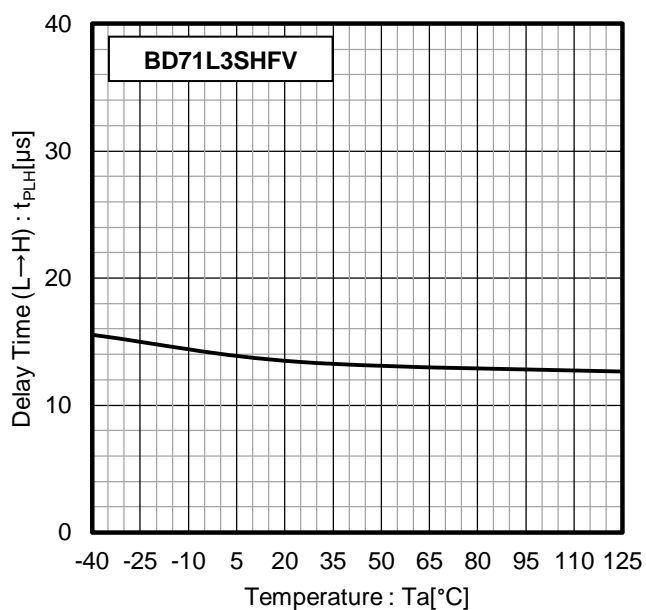


Figure 10. Delay Time (L→H) vs Temperature

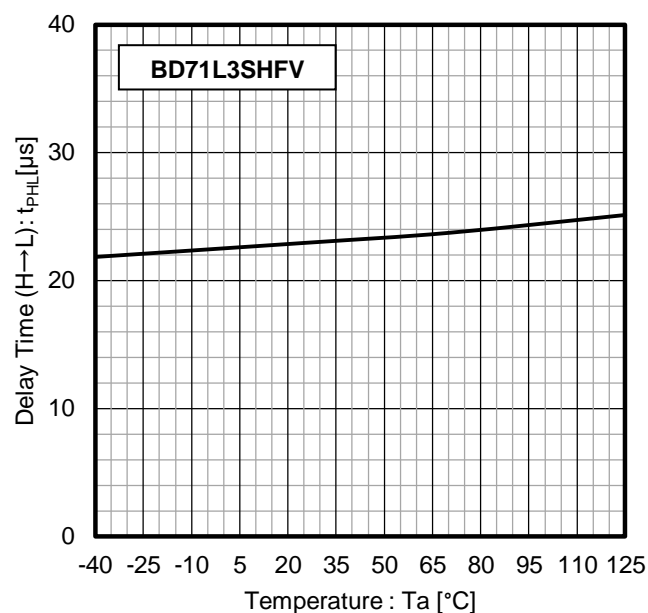
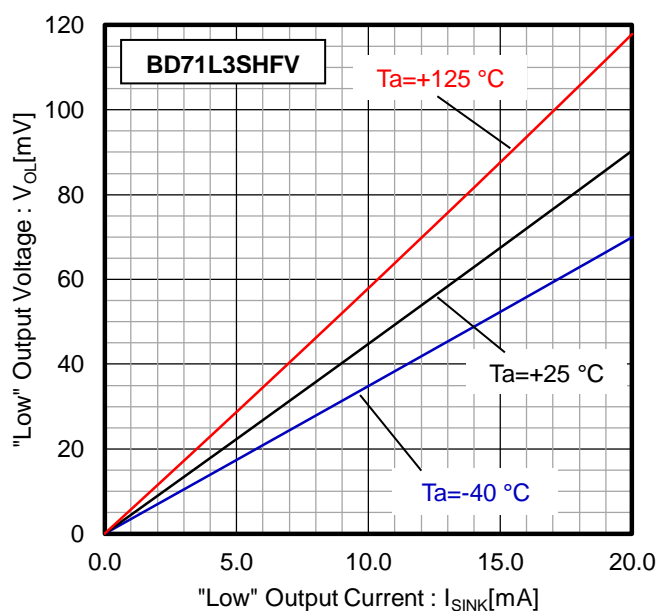


Figure 11. Delay Time (H→L) vs Temperature

Figure 12. "Low" Output Voltage vs "Low" Output Current
($V_{DD}=4.0\text{ V}$)

Application Information

Operation Description

Consider the detection and release voltage are used as the threshold voltages. When the voltage applied to V_{DD} reaches the respective threshold voltage, V_{OUT} level will change from "H" to "L" and from "L" to "H". Since the output pattern in BD71L3SHFV is an open-drain system, a pull-up resistor has to be connected to V_{DD} or other power supply. (The output (V_{OUT}) "H" voltage in this case becomes V_{DD} or other power supply voltage.)

Timing Waveform

The following shows the relationship between the input voltage V_{DD} and the output voltage V_{OUT} when the power supply voltage V_{DD} is swept up and swept down.

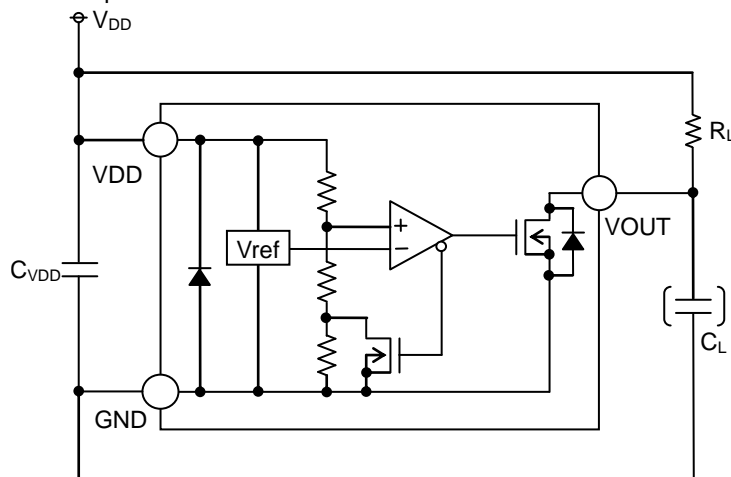


Figure 13. BD71L3SHFV Set-up Diagram

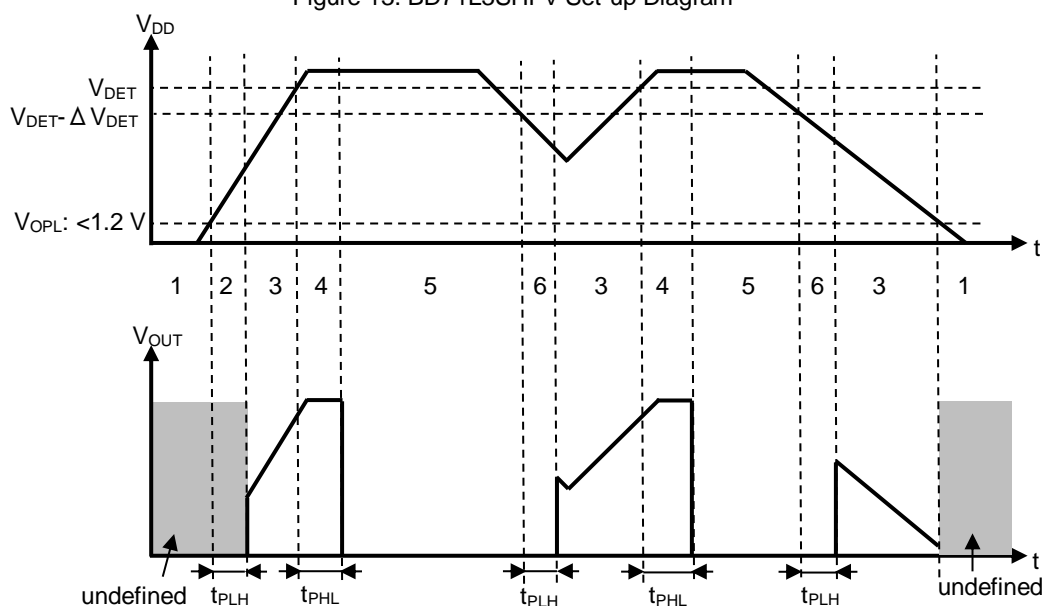


Figure 14. Timing Diagram

Operating Conditions Explanation

1. When the power supply turns on, the Output Voltage (V_{OUT}) becomes unstable until V_{DD} exceeds the Minimum Operating Voltage (V_{OPL}).
2. When V_{DD} exceeds V_{OPL} , delay time (t_{PLH}) happens, then V_{OUT} changes to "H". However, this change depends on the V_{OUT} rise time when the power supply starts up, so thorough confirmation is required.
3. V_{OUT} keeps "H".
4. When V_{DD} exceeds the Detection Voltage (V_{DET}), delay time (t_{PHL}) happens, then V_{OUT} switches from "H" to "L".
5. V_{OUT} keeps "L".
6. When V_{DD} drops below Release Voltage ($V_{DET} - \Delta V_{DET}$), delay time (t_{PLH}) happens, then V_{OUT} switches from "L" to "H".

Since this IC have hysteresis width is 30 mV(Typ), when V_{DD} fluctuates near V_{DET} , V_{OUT} switches repeatedly with "H"→"L"→"H"→"L". As a counter measure, it is recommended to use capacitor (C_{VDD}). Perform sufficient evaluation before deciding the capacitor value since the capacitance needs to be adjusted according to the amount of power supply voltage fluctuation.

Application Information – continued

Bypass Capacitor for Noise Rejection

For the stable operation of the IC, put capacitor between the VDD and GND pin and connect it closer to the pin as possible. When using extremely big capacitors, the transient response speed becomes slow so please thoroughly check.

External Parameters

The recommended value of pull-up resistance value is 50 kΩ to 1 MΩ. Since the changes are brought by many factors (circuit configuration, board layout, etc.) when using, ensure that confirmation of the real function was carried out.

In addition, this IC has high impedance design. So depending on the condition of use, this may be affected by small leak current due to the uncleanness of PCB surface. For example, if a 10 MΩ leakage is assumed between the VOUT and GND pin, it is recommended to set the value of pull up resistor less than or equal to 1/10 of the impedance of assumed leakage route.

Behavior at less than the Operating Voltage Limit

When V_{DD} falls less than the minimum operating voltage, output will be undefined. When output is connected to pull-up voltage, output will be equivalent to pull-up voltage.

Precautions when Steep Power Supply Rise

In case of a steep power supply rise, the output may toggle to “Low” once like as shown in Figure 15. This is due to the undefined output when the supply is less than the minimum operating voltage of the IC. When this waveform affects the application, make the rise time slower by attaching capacitor to V_{DD} (C_{VDD}). As a reference value, the recommended V_{DD} Rise Time is 200 μs or more.

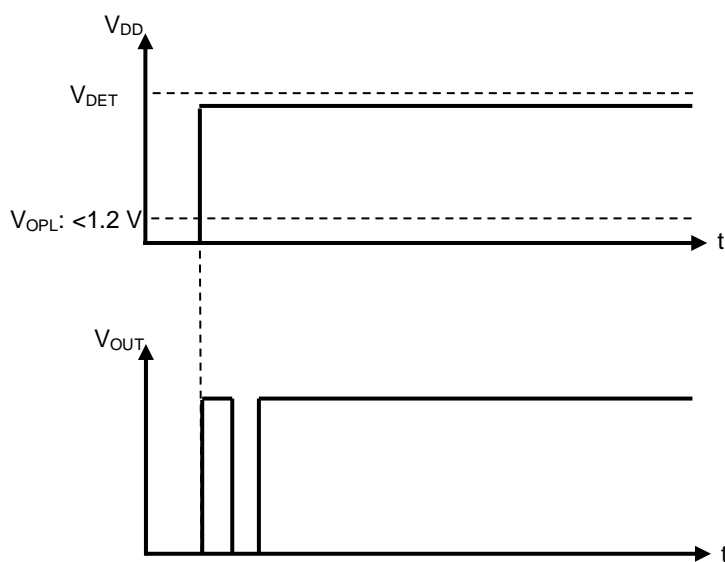


Figure 15. Steep Power Supply Rise Response

Application Examples

(1) Examples of common application circuits

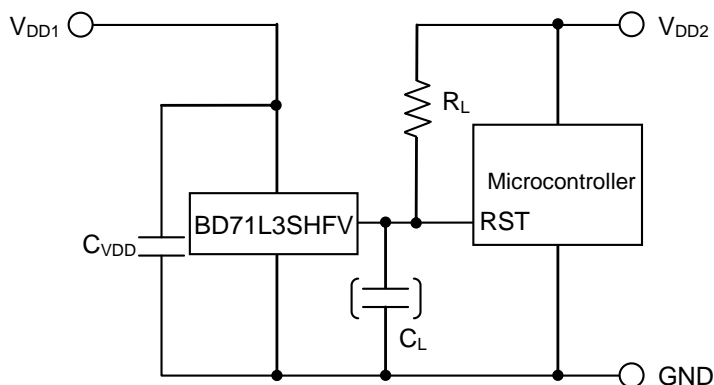


Figure 16. Examples of common application circuits

CASE1: If the power supply of the microcontroller (V_{DD2}) differs from the power supply of the detection (V_{DD1}), use the load resistance R_L connected to V_{DD2} in the output as shown in Figure 16.

CASE2: If the power supply of the microcontroller is the same as the power supply of the detection (V_{DD1}), use the R_L connected to V_{DD1} .

When connecting a capacitor C_L for noise elimination and for setting the output delay time to the VOUT pin (reset signal input pin of microcontroller), the waveform is dull during rising and falling of the output so use after confirmation that there is no problem.

(2) The following is an example of an OR connection between two types of detection voltage resets the microcontroller.

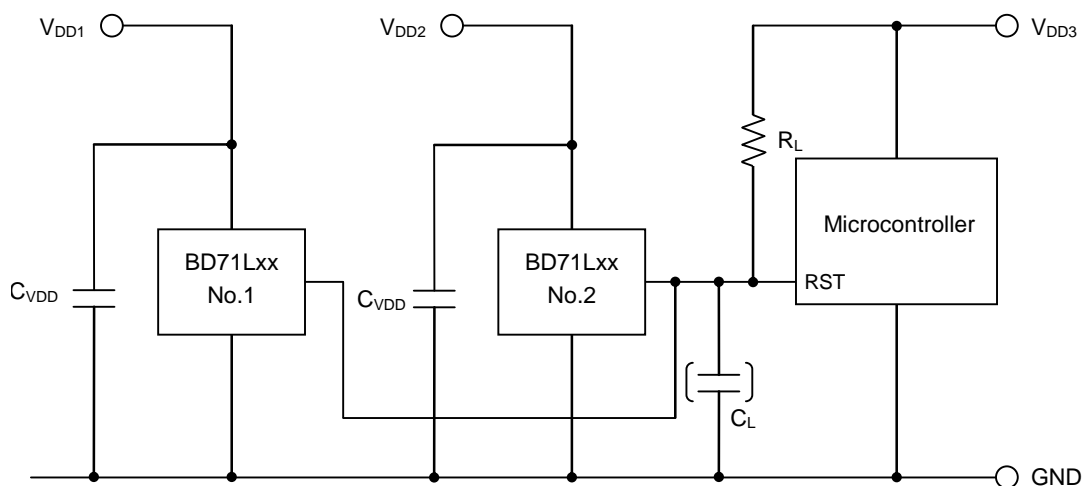


Figure 17. OR Circuit Connection Application

There are multiple power supply in the system, and in case monitoring for each independent power supply V_{DD1} and V_{DD2} and reset of micro-controller is required, an application where output "H" voltage is aligned to the microcontroller power supply V_{DD3} is possible by connecting OR application and pull-up at random voltage (V_{DD3}) such as shown in Figure 17.

Application Examples – continued

(3) Examples of the power supply with resistor dividers

In some applications, the power supply voltage of an IC comes from a resistor divider circuit. An inrush current will flow into the circuit when the output level switches from “Low” to “High” or vice versa. Inrush current is a sudden surge of current that flows from the power supply (V_{DD}) to ground (GND) as the output logic changes its state. This current flow may cause malfunction in the systems operation such as output oscillations, etc.

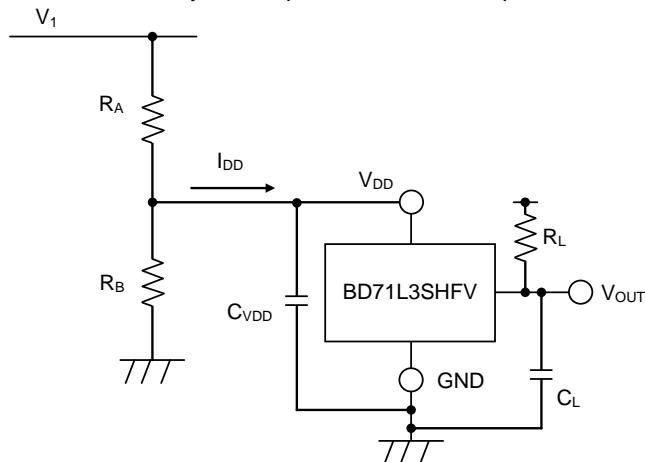
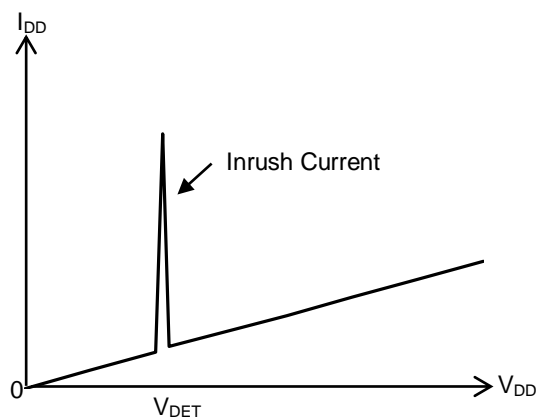


Figure 18. Resistor Divider Connection Application

Figure 19. Current Consumption vs V_{DD} Voltage

A voltage drop [$\text{Inrush current } (I_{DD}) \times [\text{input resistor } (R_A)]$] is caused by the inrush current when the output switches from “H”→“L”, and causes the input voltage to drop. When the input voltage drops and falls below the release voltage, the output will switch from “L”→“H”. At this time, the inrush current stops flowing through at output “H”, and the voltage drop disappears. As a result, the output switches from “H”→“L”, which again causes the inrush current to flow and the voltage to drop. This operation repeats and leads to oscillation.

In case resistor divider is not use and only use R_A , same response will happen.

(Attention)

Since there is small hysteresis width, it is not advisable to use it in circuit that connects the resistance to the input side. When using it, set the circuit configuration and constants in the actual application after a thorough evaluation is carried out.

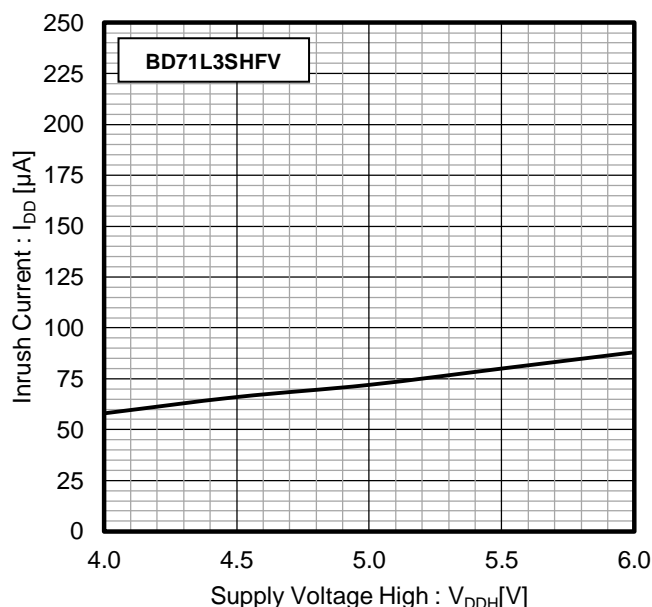


Figure 20. Open Drain Output Inrush Current
(V_{OUT} Pull-up to V_{DD} , $R_L=100\text{ k}\Omega$, $V_{DD}=1\text{ V}\rightarrow V_{DDH}$, $T_a=25\text{ }^\circ\text{C}$)

Considerations on Input and Output Capacitor

It is suggested to use input and output capacitors which is positioned as near as possible to the pins. The capacitor between the input pin and GND is effective when the power supply impedance increases or when the wiring is long. A large capacitor at the output improves stability and output load characteristics. Before implementation, check the state of mounting. In addition, the ceramic capacitor deviates in general and has temperature characteristics and AC bias characteristics. Furthermore, depending on the usage, the capacitance value decreases over time. It is recommended that ceramic capacitor to use is decided after gathering detailed data information by consulting brand manufacturers.

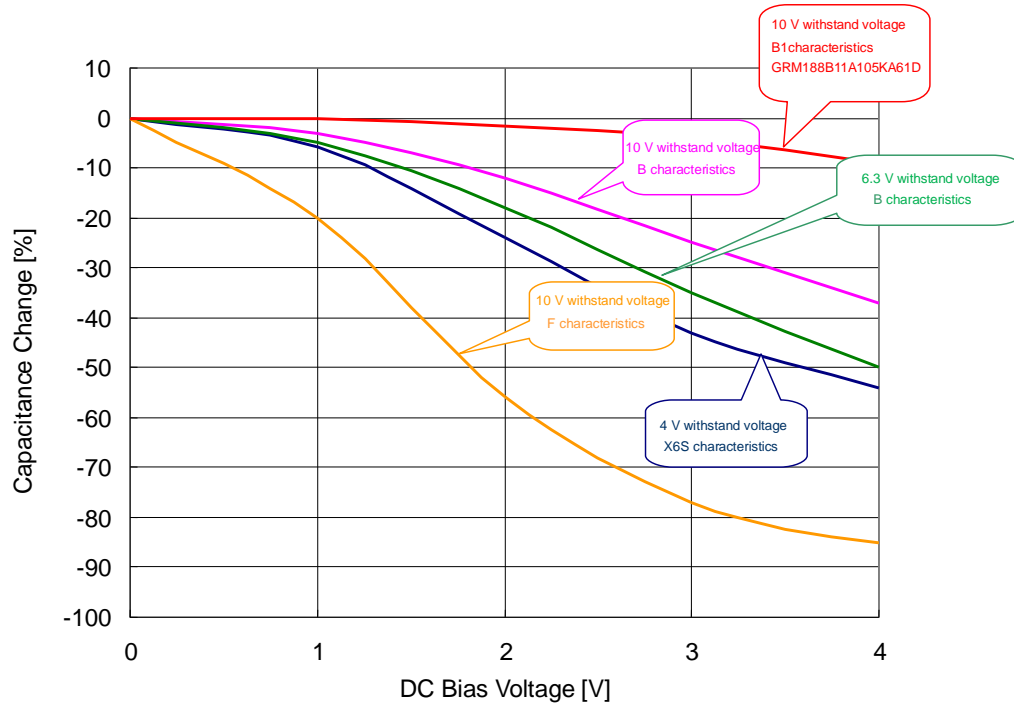


Figure 21. Ceramic Capacitance Change - DC Bias Properties
(Characteristic example)

Operational Notes

1. Reverse Connection of Power Supply

Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply pins.

2. Power Supply Lines

Design the PCB layout pattern to provide low impedance supply lines. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

3. Ground Voltage

Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

4. Ground Wiring Pattern

When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

5. Recommended Operating Conditions

The function and operation of the IC are guaranteed within the range specified by the recommended operating conditions. The characteristic values are guaranteed only under the conditions of each item specified by the electrical characteristics.

6. Inrush Current

When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

7. Testing on Application Boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

8. Inter-pin Short and Mounting Errors

Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

9. Unused Input Pins

Input pins of an IC are often connected to the gate of a MOS transistor. The gate has extremely high impedance and extremely low capacitance. If left unconnected, the electric field from the outside can easily charge it. The small charge acquired in this way is enough to produce a significant effect on the conduction through the transistor and cause unexpected operation of the IC. So unless otherwise specified, unused input pins should be connected to the power supply or ground line.

10. Regarding the Input Pin of the IC

In the construction of this IC, P-N junctions are inevitably formed creating parasitic diodes or transistors. The operation of these parasitic elements can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions which cause these parasitic elements to operate, such as applying a voltage to an input pin lower than the ground voltage should be avoided. Furthermore, do not apply a voltage to the input pins when no power supply voltage is applied to the IC. Even if the power supply voltage is applied, make sure that the input pins have voltages within the values specified in the electrical characteristics of this IC.

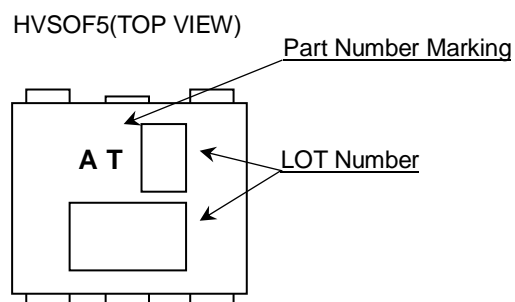
11. Ceramic Capacitor

When using a ceramic capacitor, determine a capacitance value considering the change of capacitance with temperature and the decrease in nominal capacitance due to DC bias and others.

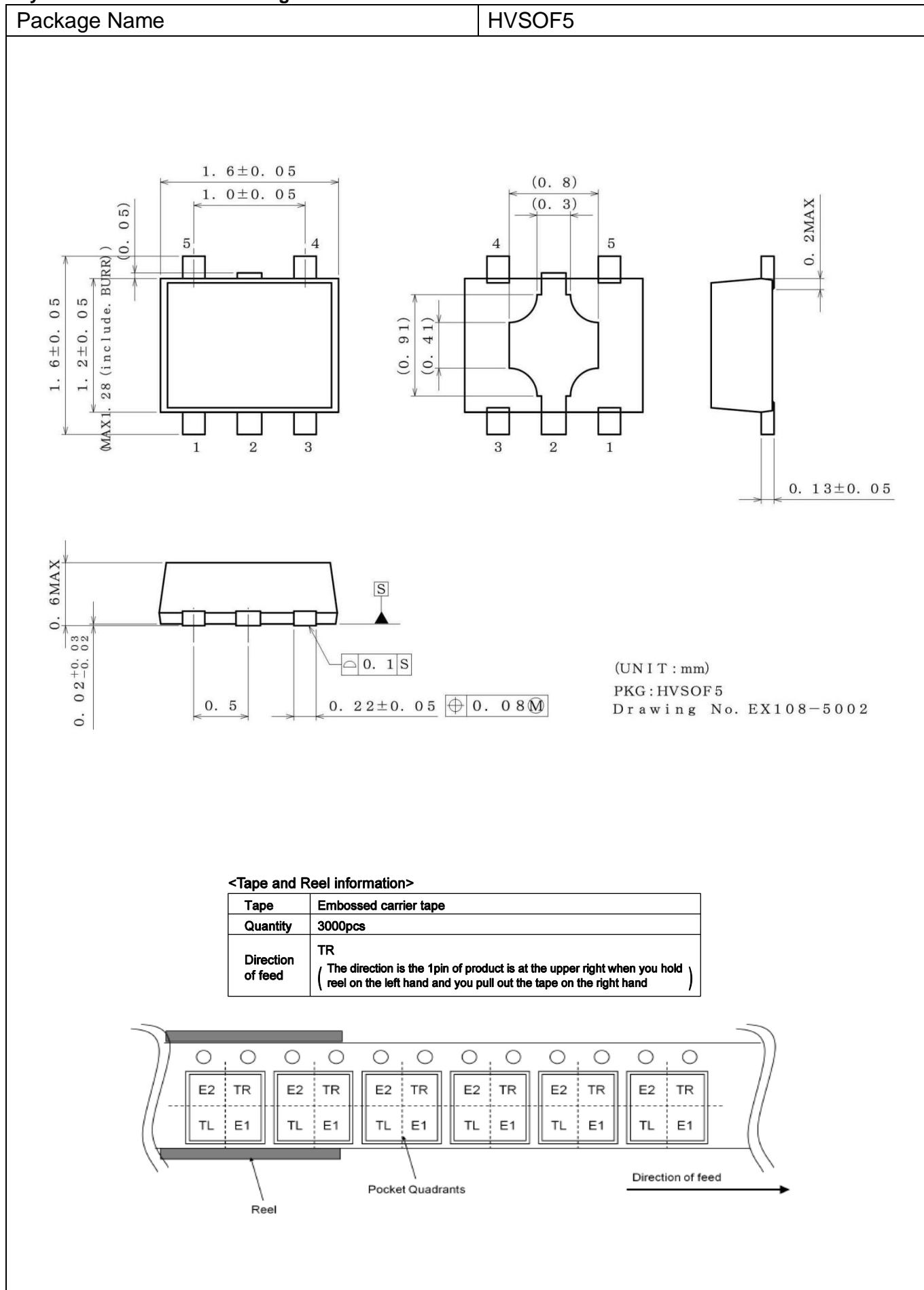
Ordering Information

B	D	7	1	L	3	S	H	F	V	-	T	R
Package HFV: HVSOF5										Packing and Forming Specification TR: Embossed tape and reel		

Marking Diagram



Physical Dimension and Packing Information



Revision History

Date	Revision	Changes
22.Aug.2018	001	New Release

Notice

Precaution on using ROHM Products

- Our Products are designed and manufactured for application in ordinary electronic equipment (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment ^(Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	CLASS III
CLASS IV		CLASS III	

- ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
 - Installation of protection circuits or other protective devices to improve system safety
 - Installation of redundant circuits to reduce the impact of single or multiple circuit failure
- Our Products are designed and manufactured for use under standard conditions and not under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc. prior to use, must be necessary:
 - Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
 - Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - Sealing or coating our Products with resin or other coating materials
 - Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - Use of the Products in places subject to dew condensation
- The Products are not subject to radiation-proof design.
- Please verify and confirm characteristics of the final or mounted products in using the Products.
- In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of ionizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

Precaution for Product Label

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

Precaution for Foreign Exchange and Foreign Trade act

Since concerned goods might be fallen under listed items of export control prescribed by Foreign exchange and Foreign trade act, please consult with ROHM in case of export.

Precaution Regarding Intellectual Property Rights

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General Precaution

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